

## EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S1	4	"20040041958" "20020117691" "6043511".pn.	US- PGPUB; USPAT	OR	ON	2007/01/24 14:19
S2	190	LG.as. and copper.clm.	US- PGPUB; USPAT	OR	ON	2007/02/02 14:40
S4	1	"20030155373"	US- PGPUB; USPAT	OR	ON	2007/02/02 14:54
S3	23	"349".clas. and LG.as. and copper.clm.	US- PGPUB; USPAT	OR	ON	2007/02/02 15:52
S5	16	"349".clas. and LG.as. and cu.clm.	US- PGPUB; USPAT	OR	ON	2007/02/02 16:45
S6	1	"6043511".pn.	US- PGPUB; USPAT	OR	ON	2007/02/07 14:24
S11	3	("20020057395" "20020081847" "20020105604" "20020117691" "20020135710" "20030127649" "20030169380" "20030178656" "20030213966" "6043511" "6335211" "6350995" "6362507" "6674495" "6780784" "6861368").pn. not (copper cu)	US- PGPUB; USPAT	OR	ON	2007/02/07 15:24

S10	13	("20020057395" "20020081847" "20020105604" "20020117691" "20020135710" "20030127649" "20030169380" "20030178656" "20030213966" "6043511" "6335211" "6350995" "6362507" "6674495" "6780784" "6861368").pn. and (copper cu)	US- PGPUB; USPAT	OR	ON	2007/02/07 15:24
S13	3	("6750475" "5650834" "6674495").pn. and (cu copper)	US- PGPUB; USPAT	OR	ON	2007/02/07 15:38
S14	1	"6323490".pn.	US- PGPUB; USPAT	OR	ON	2007/02/07 17:07
S16	37	"349".clas. and taper with gate adj electrode	US- PGPUB; USPAT	OR	ON	2007/02/07 17:08
S17	1	"6350995".pn.	US- PGPUB; USPAT	OR	ON	2007/02/07 17:39
S21	50	"349".clas. and adhesion with gate with substrate	US- PGPUB; USPAT	OR	ON	2007/02/08 16:00
S30	92	349/38,39.ccls. and @pd< "20020630" and passivation	US- PGPUB; USPAT	OR	ON	2007/02/08 16:48
S32	56	(hwang-yong-sup chae- gee-sung jo-gyoo-chul) and (copper cu).clm.	US- PGPUB; USPAT	OR	ON	2007/07/29 12:34
S35	89	(hwang-yong-sup chae- gee-sung jo-gyoo-chul) not (copper cu).clm.	US- PGPUB; USPAT	OR	ON	2007/07/29 12:43
S38	1	(hwang-yong-sup chae- gee-sung jo-gyoo-chul) and (copper cu).clm. and @pd> "20070729"	US- PGPUB; USPAT	OR	ON	2008/01/08 15:28
S39	6	(hwang-yong-sup chae- gee-sung jo-gyoo-chul) not (copper cu).clm. and @pd> "20070729"	US- PGPUB; USPAT	OR	ON	2008/01/08 15:29

S49	5	(hwang-yong-sup chae-gee-sung jo-gyoo-chul) and (copper cu).clm. and @pd> "20080108"	US-PGPUB; USPAT	OR	ON	2008/07/17 19:51
S50	11	(hwang-yong-sup chae-gee-sung jo-gyoo-chul) not (copper cu).clm. and @pd> "20080108"	US-PGPUB; USPAT	OR	ON	2008/07/17 19:52
S57	16	349/147,148.ccls. and @ad< "20020903" and (Cu copper) with (Ta Ti tantalum titanium) with (Mo molybdenum) with (source drain gate data signal bus line electrode)	US-PGPUB; USPAT	OR	ON	2008/07/17 20:00
S58	10	349/147,148.ccls. and @ad< "20020903" and schechter	US-PGPUB; USPAT	OR	ON	2008/07/17 20:18
S64	12	(hwang-yong-sup chae-gee-sung jo-gyoo-chul) not (cu copper).clm. and @pd> "20080717"	US-PGPUB; USPAT	OR	ON	2009/02/12 16:17
S63	4	(hwang-yong-sup chae-gee-sung jo-gyoo-chul) and (cu copper).clm. and @pd> "20080717"	US-PGPUB; USPAT	OR	ON	2009/02/12 16:17
L2	1	"6674502".pn.	US-PGPUB; USPAT	OR	ON	2009/02/20 13:48
L3	4	"349".das. and etch\$4 with protect\$3 with substrate with (SiN or nitride) adj layer	US-PGPUB; USPAT	OR	ON	2009/02/20 13:51
L4	5	"349".das. and etch\$4 with protect\$3 adj3 substrate with (SiN or nitride)	US-PGPUB; USPAT	OR	ON	2009/02/20 13:52
L5	11	"349".das. and protect\$3 adj3 substrate with (SiN or nitride)	US-PGPUB; USPAT	OR	ON	2009/02/20 13:53
L6	19	"349".das. and undercoat with substrate with (SiN or nitride)	US-PGPUB; USPAT	OR	ON	2009/02/20 13:54
L7	64	"349".das. and etch\$4 with damag\$3 with substrate	US-PGPUB; USPAT	OR	ON	2009/02/20 13:56

L8	3	"349".clas. and (etch\$4 with damag\$3 with substrate) same (SiN nitride)	US-PGPUB; USPAT	OR	ON	2009/02/20 14:16
L9	3	"20040233361" "6509616".pn.	US-PGPUB; USPAT	OR	ON	2009/02/20 14:18
L10	2	"349".clas. and (etch\$4 with buffer with substrate) same (SiN nitride)	US-PGPUB; USPAT	OR	ON	2009/02/20 14:20
L18	36	(US-20030107023-\$ or US-20040209407-\$ or US-20040125257-\$ or US-20030178656-\$ or US-20040262569-\$ or US-20020117691-\$ or US-20040041958-\$ or US-20060105579-\$ or US-20040263706-\$ or US-20020081847-\$ or US-20040263708-\$ or US-20050041170-\$ or US-20030127649-\$ or US-20020042167-\$ or US-20040263746-\$ or US-20050122443-\$ or US-20080182352-\$ or US-20010055084-\$).did. or (US-7176535-\$ or US-6323490-\$ or US-6429908-\$ or US-6674502-\$ or US-6043511-\$ or US-5739877-\$ or US-7008548-\$ or US-7061020-\$ or US-6861368-\$ or US-6462802-\$ or US-6091464-\$ or US-6674495-\$ or US-5429962-\$ or US-5650834-\$ or US-6750475-\$ or US-7277138-\$ or US-7352417-\$ or US-6184964-\$).did.	US-PGPUB; USPAT	OR	ON	2009/02/20 14:32
L19	56	"349".clas. and (etch\$4 with (Ti Ta titanium tantalum)) same ((nitride SiN) with substrate)	US-PGPUB; USPAT	OR	ON	2009/02/20 14:35
L20	33	349/147,148.ccls. and @ad<"20020903" and (Cu copper) with (Ta Ti tantalum titanium)	US-PGPUB; USPAT	OR	ON	2009/02/20 15:21

2/20/09 3:42:45 PM

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